

OPTICAL INTERCONNECTS SYMPOSIUM 2017

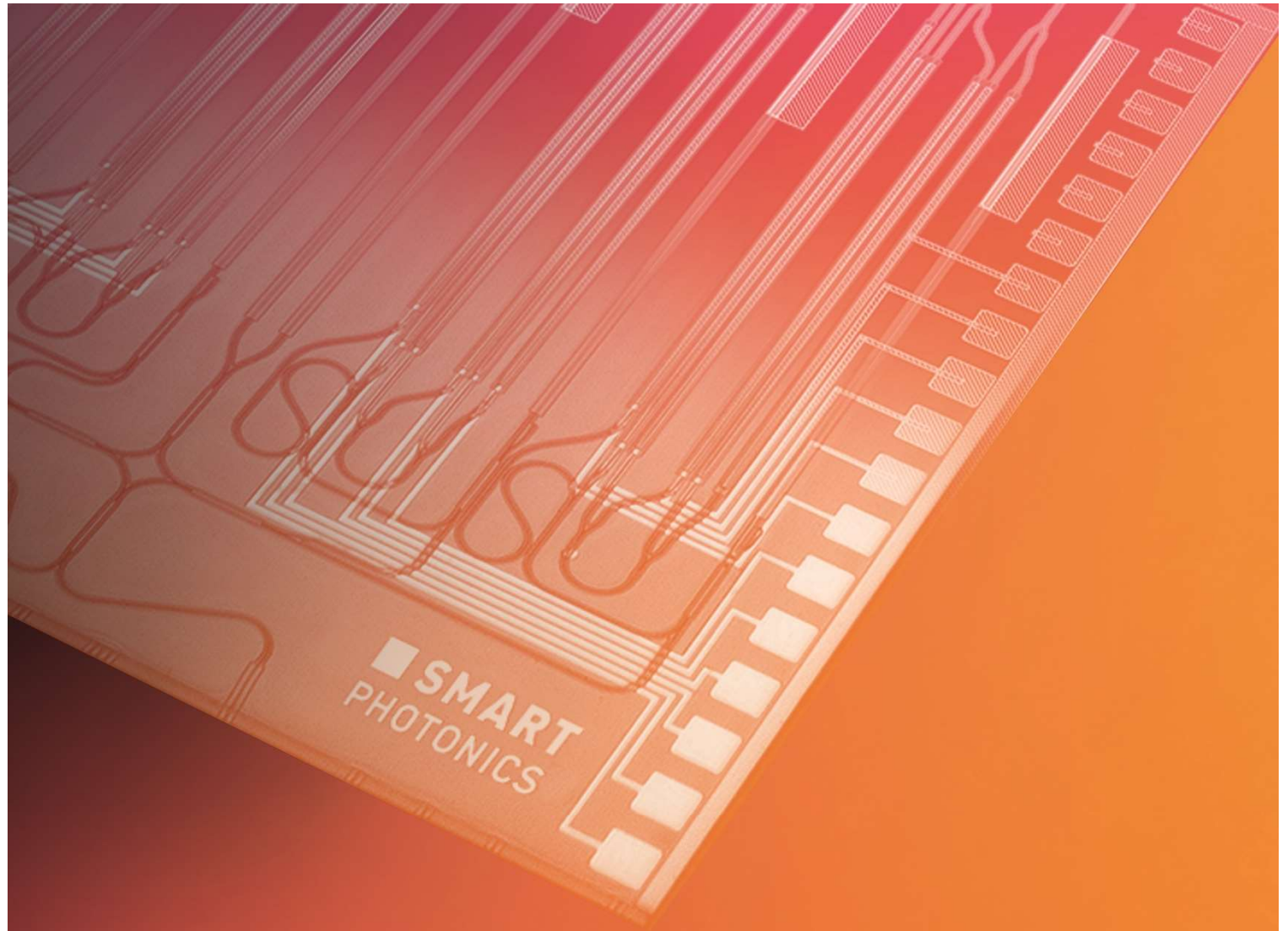
The integrated photonics revolution

Jeroen Duis



OUTLINE

- Introduction to SMART Photonics
- Photonic integration
 - Generic platform
 - Applications and examples
 - MPW service
- Processes
- Future developments
- Summary

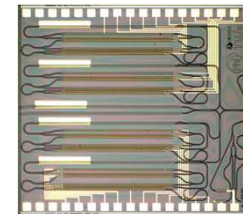
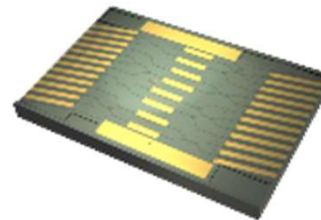
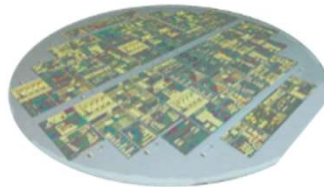
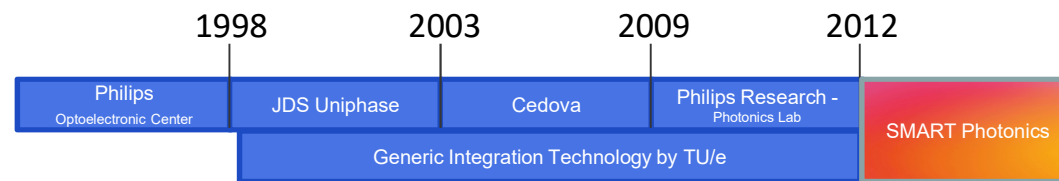


SMART PHOTONICS GENERIC INTEGRATION PLATFORM



OUR HISTORY

SMART Photonics B.V. founded in 2012



WE OFFER

- Processing services for making photonic components on InP
 - Both discrete and PICs
- Photonic components are used for
 - Tele- and Data communications
 - To meet technology requirements (Gb/s and J/bit)
 - To meet cost requirements (€/ bit and €/mm²)
 - IoT
 - Sensing applications in Medical, Aviation, Automotive, Space, Machining etc.
 - Imaging/ Spectrum analysis etc.

WE ARE MOVING FAST!

2012
Start-up



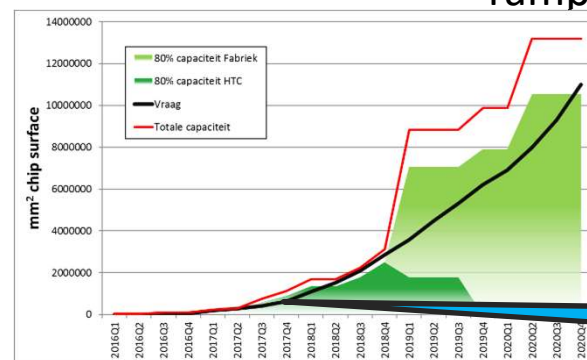
2015
Opening production
cleanroom at HTCE



2016/2017
Production
ramp-up



2019
New factory



today

OUR FACILITIES



- SMART Photonics
@High Tech Campus
 - 570m² 3" Production cleanroom (Class 1000)
 - Processing and epitaxy



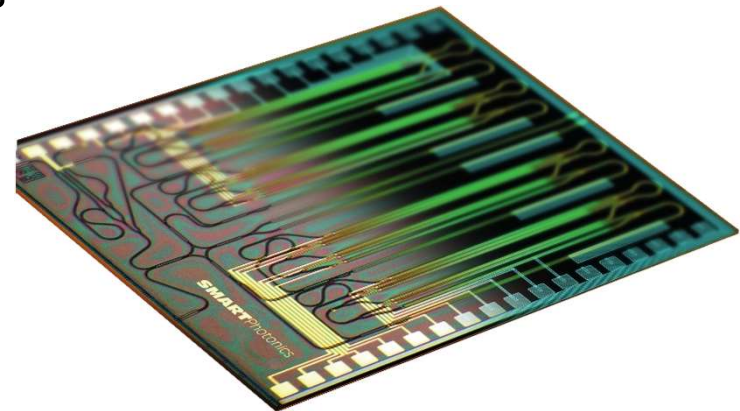
- SMART Photonics
@NanoLab cleanroom Eindhoven
 - 850m² Fully equipped R&D facility

OUR CAPABILITIES

Epitaxy	Multi-wafer MOVPE reactors for base wafer growth, regrowth and overgrowth
Lithography	High throughput, high resolution (>100 nm) - DUV scanner 0.7 µm projection litho – I-Line stepper High resolution (<100 nm) – E-beam 0.6 µm contact litho – contact aligner
Etching	Cassette-based wet etching ICP for single and multi-wafer etching RIE dedicated tools for photoresist, dielectric and polymer etching
Dielectrics	PECVD for SiO _x and SiN _x
Metallization	E-beam evaporation Sputtering Plating
Back-end	Grinding and polishing Scribe and break Optical coatings

WHAT MAKES US SPECIAL

- People
 - Knowledge and experience in photonics and semiconductor processing
- Capabilities
 - Full process from Epi to coating of facets
 - Unique tools (3" ASML scanner for high resolution litho)
- Proposition
 - Unique PIC technology
 - Buried Hetero DFB process



SEMICONDUCTORS

Products	New	Extended functionalities High tech equipment Games Medical equipment Mobile Phones	New functionalities create new applications Computers/Notebooks Tablets Smart phones Google/Facebook
	Existing	Same functionality on smaller footprint High tech applications Radio Calculator TV	Same functionality in new applications Aviation/Space applications Car and mobile radio Flat screens
		Existing	New
Markets			



9/22/2017

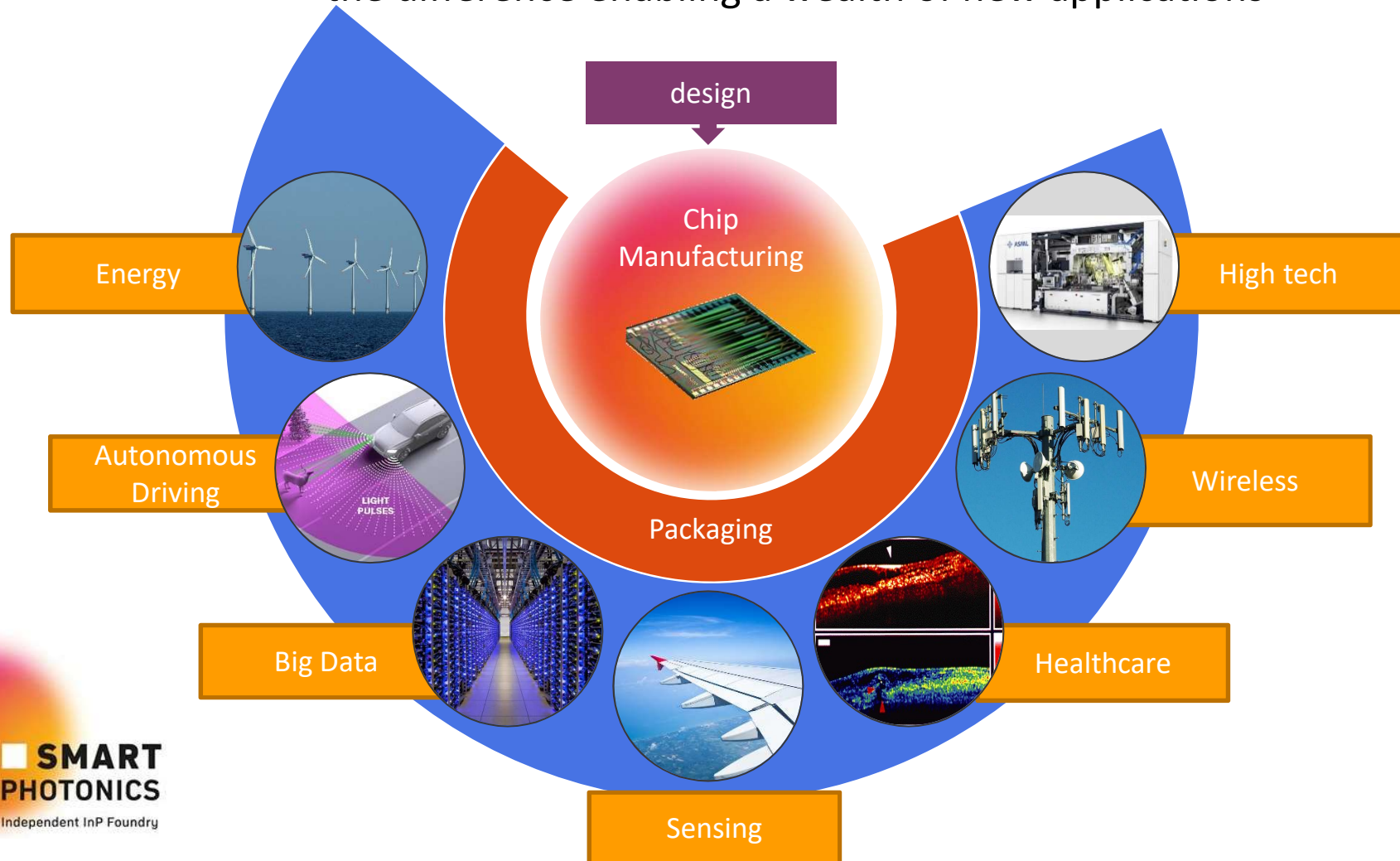


INP PHOTONICS

Products	New	Extended functionalities FBG for Medical sensing and positioning 5G Antenna systems LIDAR	New functionalities create new applications Gas detection What else?
	Existing	Same functionality on smaller footprint Sensing for high tech applications (FBG/Analyzing) Telecom/Datacom	Same functionality in new applications Fiber to the chip FBG in aviation/ pace Point of care medical analysis
		Existing	New
Markets			

PHOTONIC INTEGRATION MAKES THE DIFFERENCE!

- The SMART Photonics Generic Integration Technology makes the difference enabling a wealth of new applications

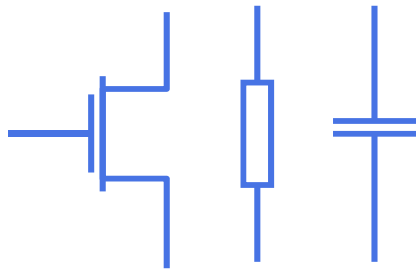


GENERIC INTEGRATION PHILOSOPHY

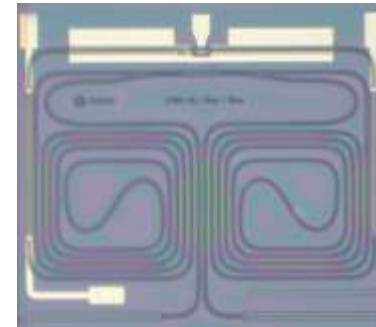
Electronic integration



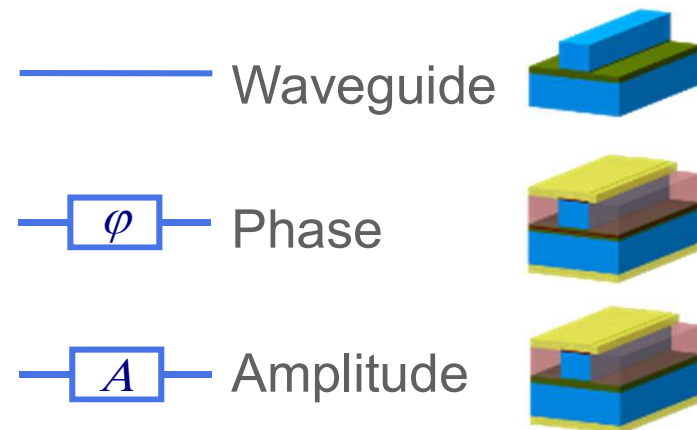
Basic elements:



Photonic integration

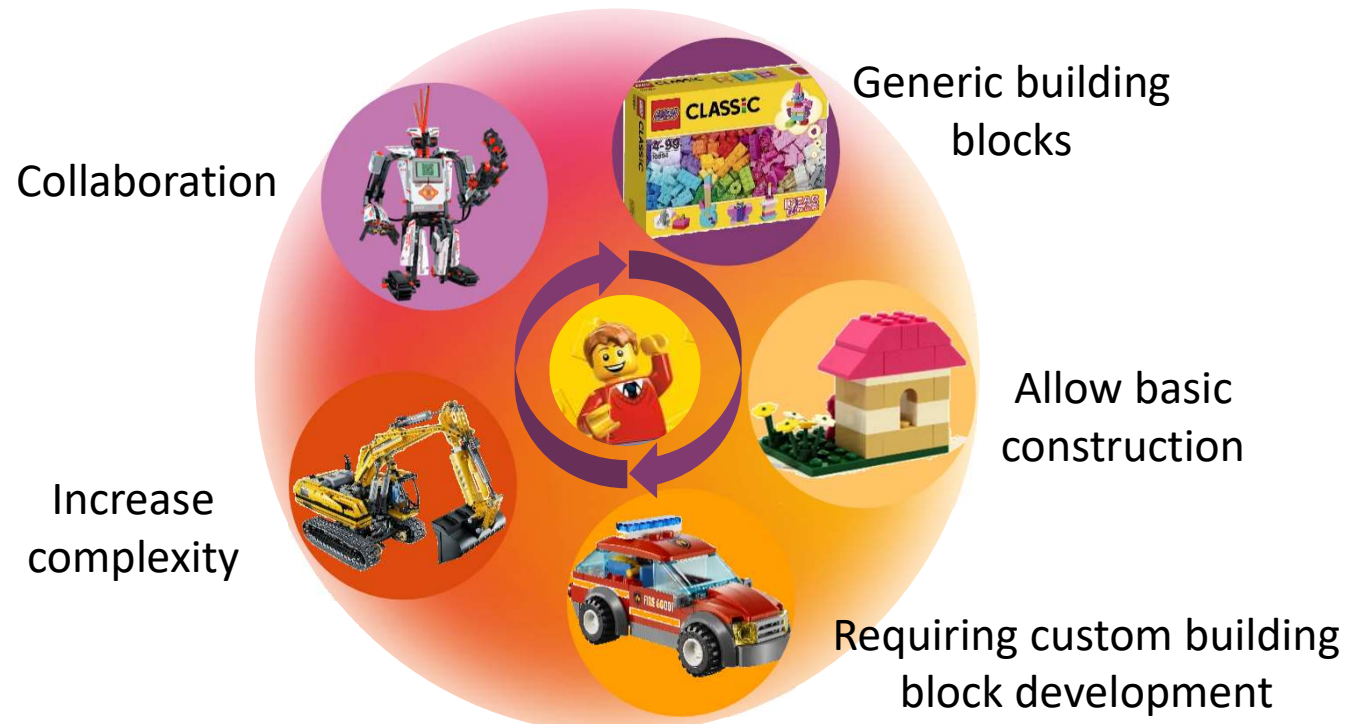


Basic elements:

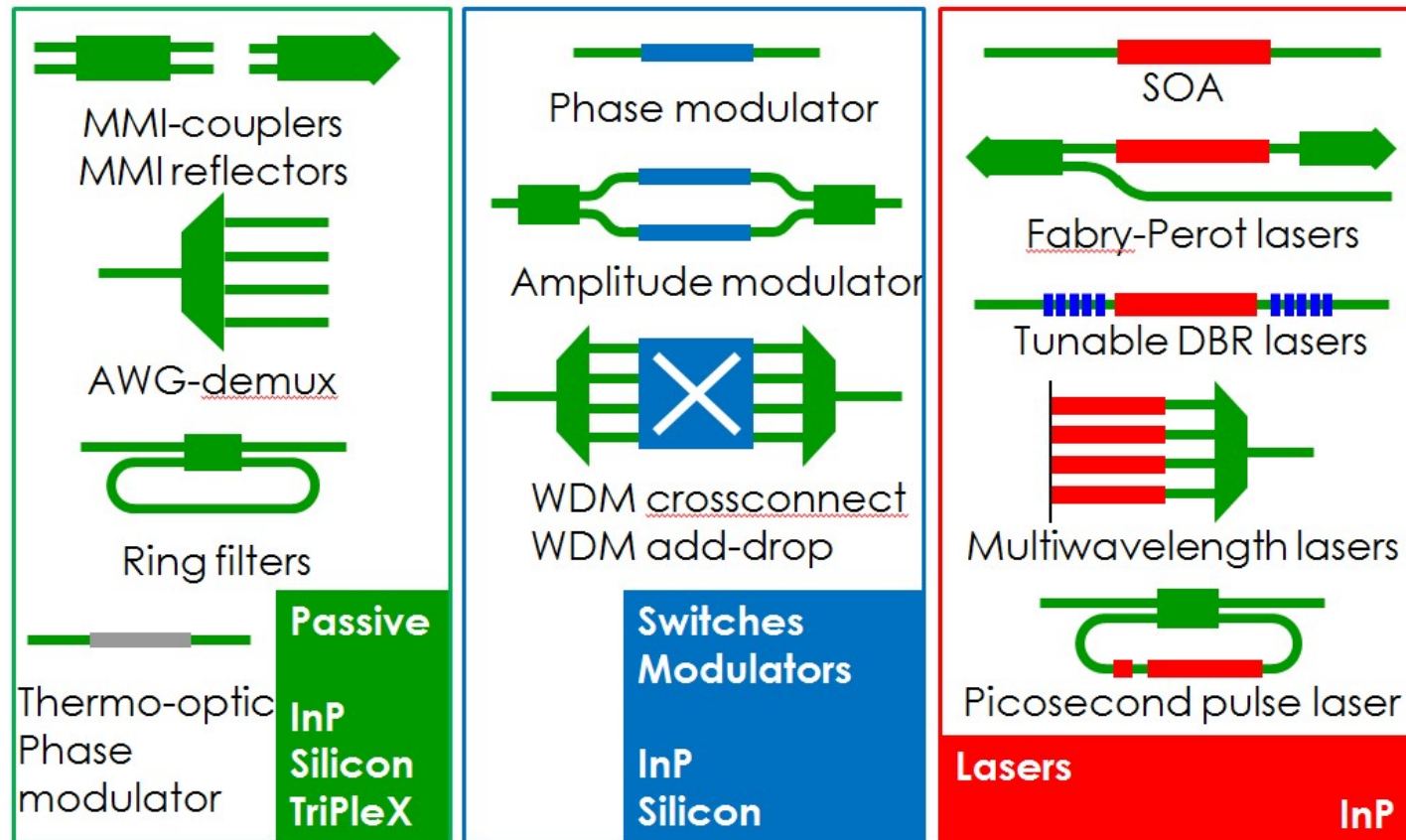


OUR GENERIC INTEGRATION PLATFORM

- *Standardized industrial* integration process
- Design on *functional level* by using *building block* approach
- Software design kits for fast and accurate design
- Multi-project wafer (MPW) runs for *fast* and *cost efficient* prototyping
- Enables *fast up-scaling* to high volume manufacturing



INP PLATFORM CAPABILITIES



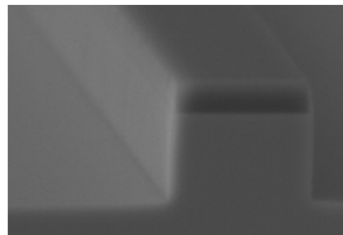
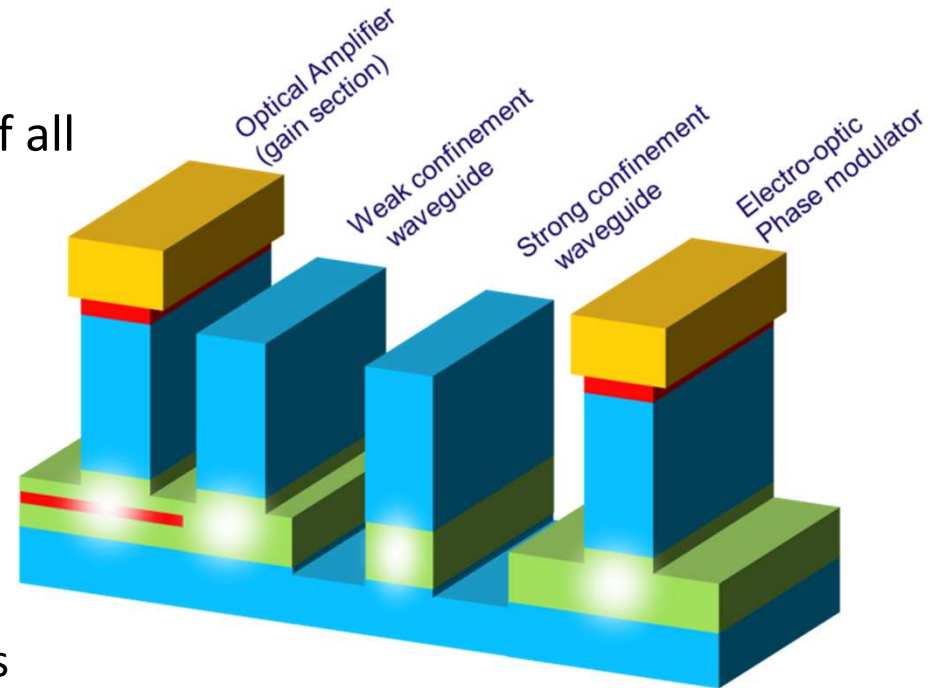
SMART PHOTONICS INTEGRATION PLATFORM

InP platform:

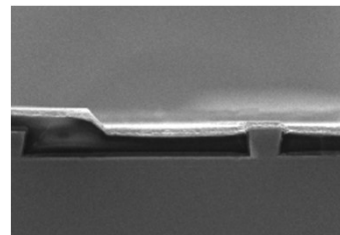
Monolithic integration of all functionalities!



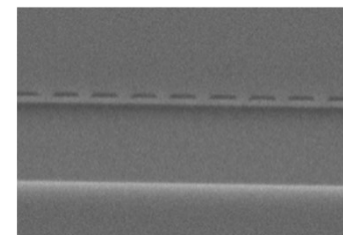
InP Si Electronics



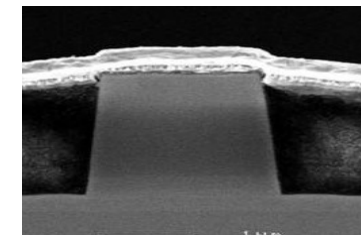
waveguides



phase modulators



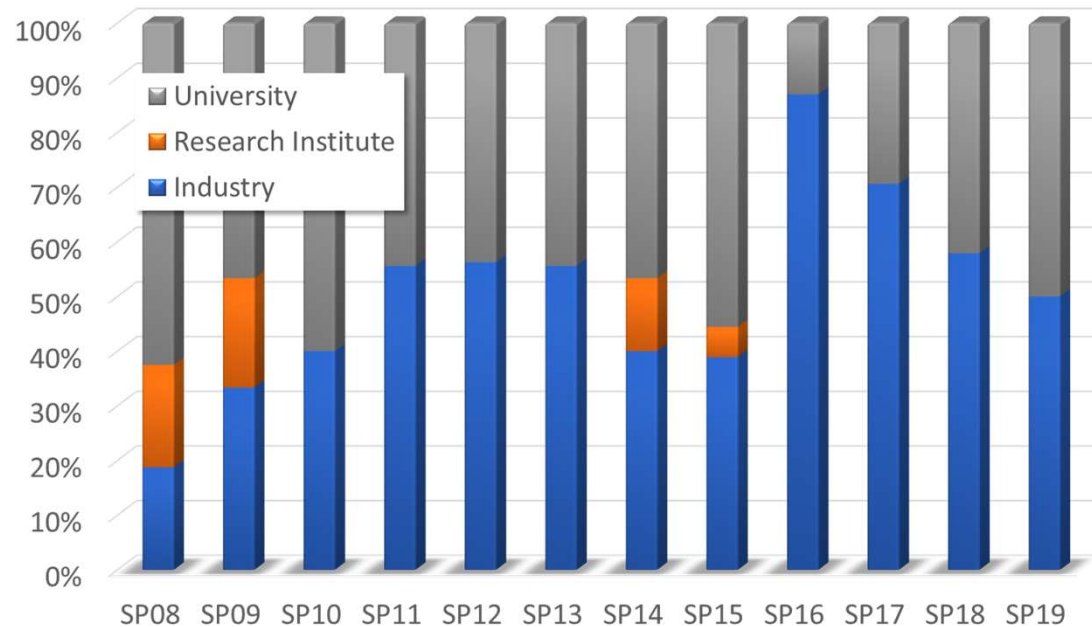
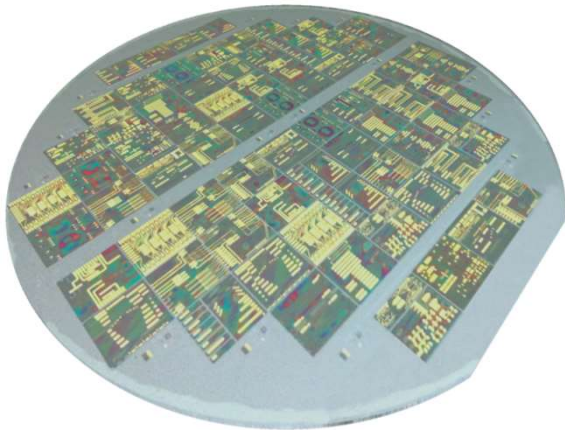
gratings



Amplifiers/ laser
gain section

OUR MPW SERVICE

- World's first commercial MPW run on InP in July 2013
- MPW run starts every quarter
- Low threshold access to a new technology
- Over 200 designs fabricated!



PDK: BUILDING BLOCK LIBRARY

- Process Design Kit is available
 - For **circuit simulation** and **mask design**
 - **Design manual** and **Functional** building block description
 - Full **layout-aware** design flow
 - Access via **state of the art software** tools



Open source, lowering barrier to enter the PIC space

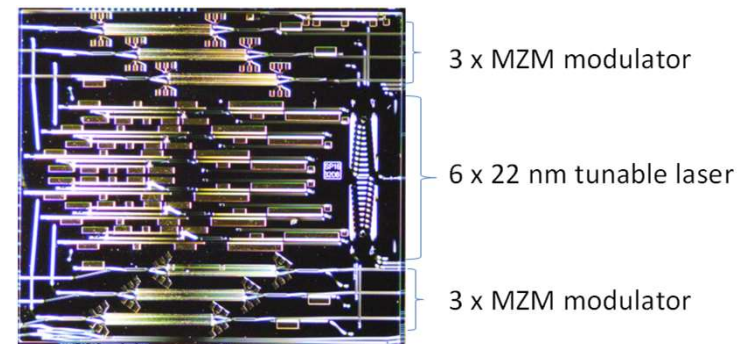
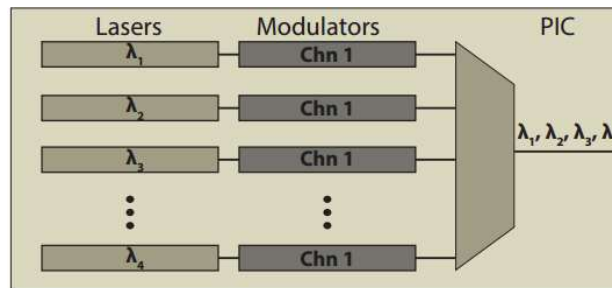
APPLY NOW FOR THE PHOTONDELTA MPW INNOVATION GRANT

- PhotonDelta, in partnership with [JePPix](#) and [Brainport Development](#), is now launching a photonics chip incentive scheme. They are reaching out to help global high-tech companies, large and small, design and build next-generation photonics chips specific to their business.
- If you're planning to fabricate your photonics chip with companies in Brabant, you may qualify for a PIC Innovation voucher, worth up to € 4,250.00. This is half the cost of an MPW run
- For more information check www.photondelta.eu

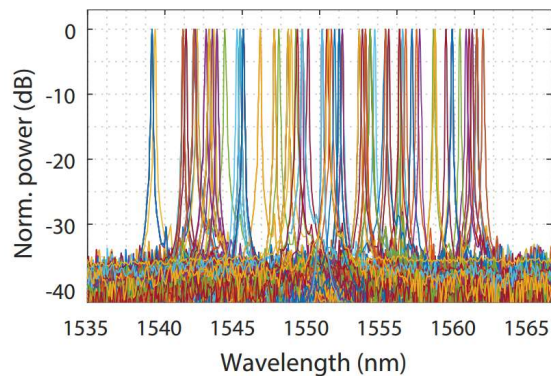


EXAMPLE: 100 GB/S TRANSMITTER

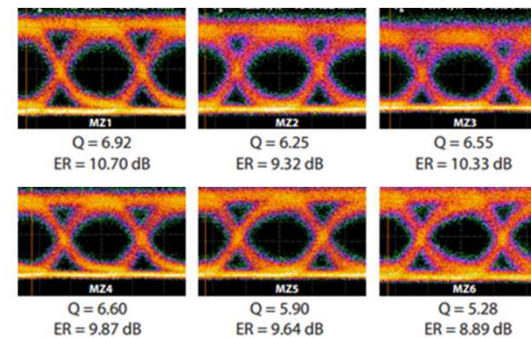
>100 Gb/s transmitter on single chip, fabricated in our powerful MPW platform



Wavelength tuning

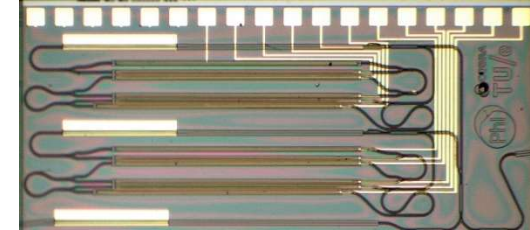
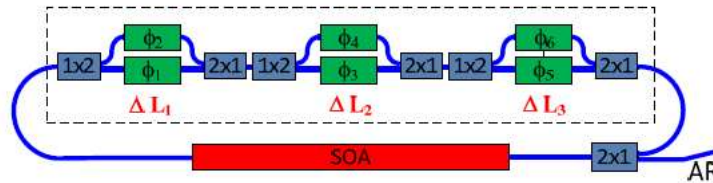


20 Gb/s per channel

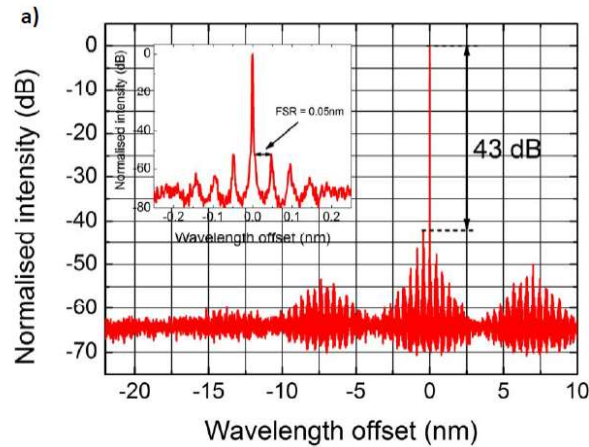


W. Yao, COBRA

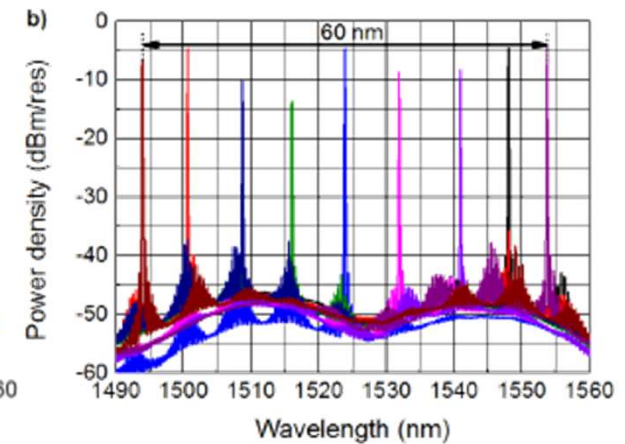
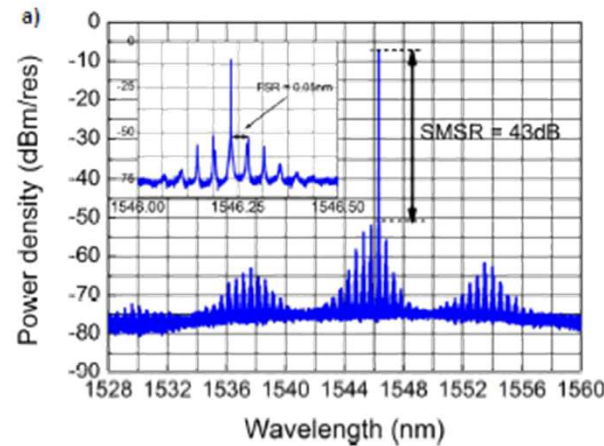
EXAMPLE: WIDELY TUNABLE LASER



Simulations



Prototype

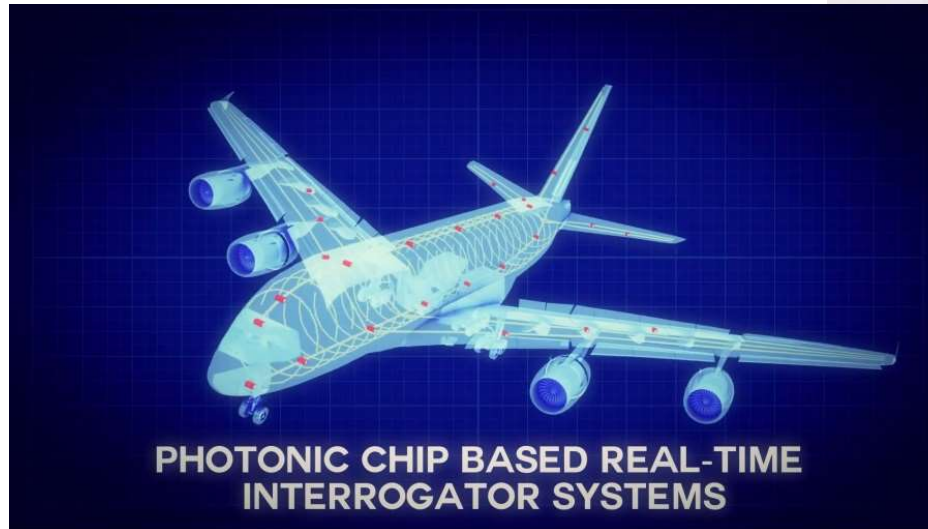


S. Latkowski, COBRA

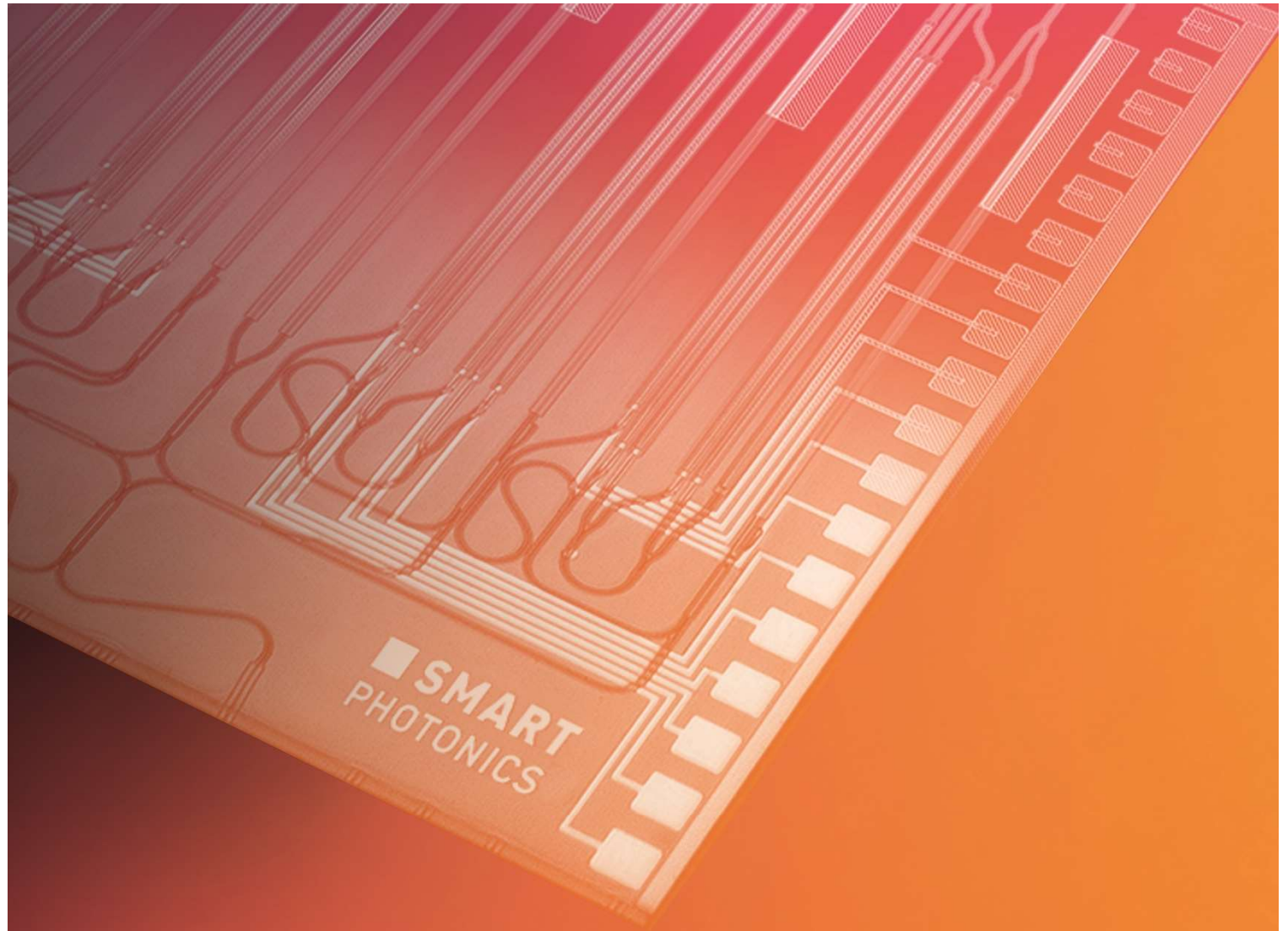
Advanced PDK allowing first-time-right prototyping

EXAMPLE: FBG INTERROGATOR

Distributed temperature and strain measurement with embedded fibers + PIC readouts



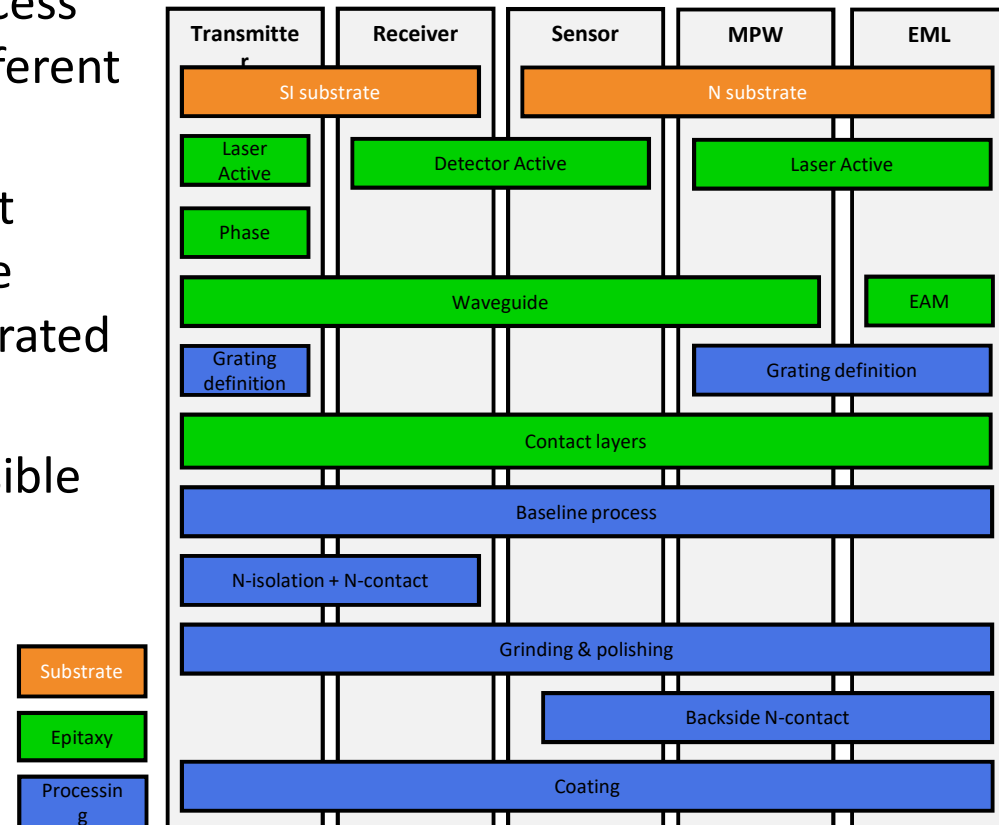
Wider possibilities for structural health monitoring



BUILDING BLOCKS

PLATFORM AND CUSTOMIZATION

- Different flavours of the generic process available for different applications
- Up to 3 different materials can be epitaxially integrated
- Customized layerstacks possible



SHORT TERM EXECUTION PLAN FOR MPW

Technologies								
	2017				2018			
	SP19	SP20	SP21	SP22	SP23	SP24	SP25	SP26
High resolution waveguide definition								
DBR Gratings								
High speed platform 30Ghz performance								
Spot Size Converter								
EAM								
Shipping				In Fab	Starting	Commercial Introduction in MPW		

- 4 month fab time -> 2 month fab time
 - Doubling number of design iterations per year from 2 to 4
- Scanner implementation -> SP20 -> All time low loss
 - 1,2 dB/cm shallow etch
 - 1,6 dB/cm deep etch
- Increased number of MPW chips from 6 to 8 for same price
- Multiple chip sizes

SUMMARY

- Generic Integration Process available
 - Transmit and receive platform
- Large range of applications demonstrated
- Commercial, low threshold access to technology via quarterly MPW runs for proof of concept
- Industrial scale, production ready process



SMART PHOTONICS

Independent InP Foundry

Meet the experts at booth #495
Contact us: sales@smartphotonics.nl